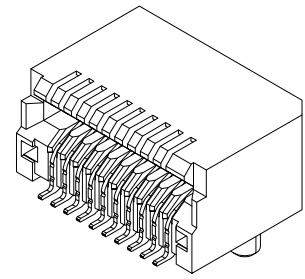
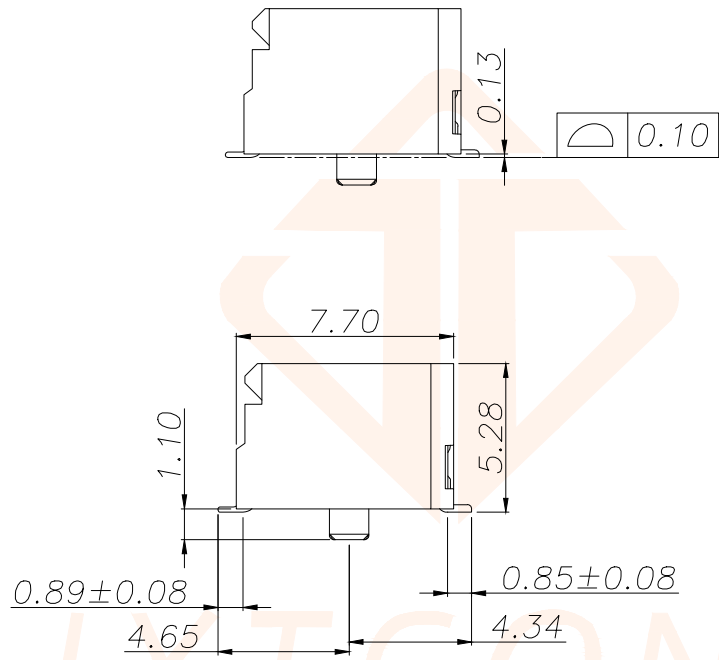
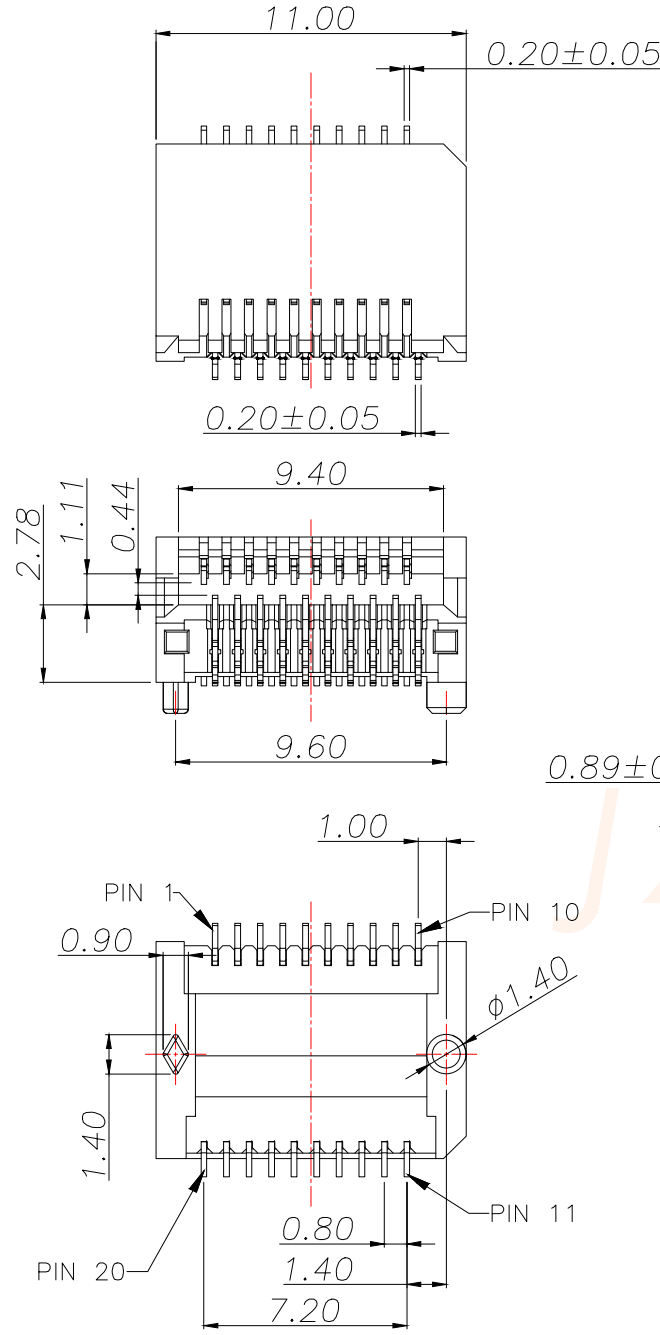




REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



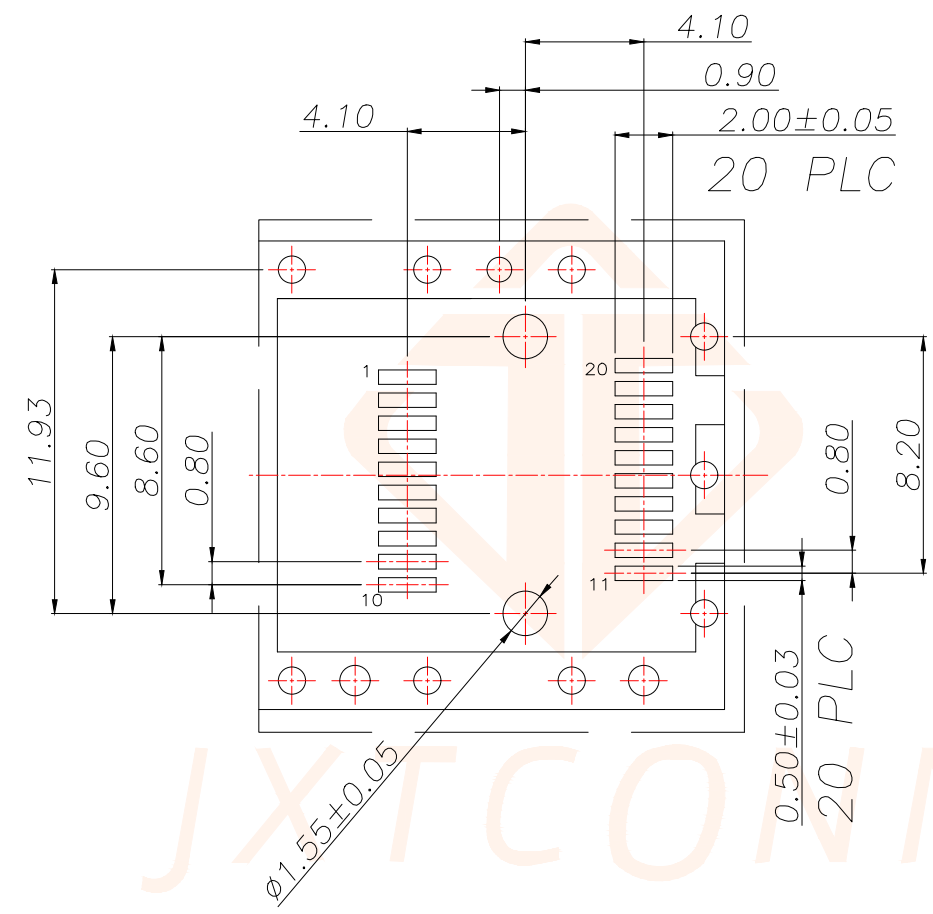
NOTES:

- 1.MATERIAL
HOUSING:HIGH TEMPERATURE LCP, Black,UL94 V-0
- 2.CONTACTS:PHOSPHOR BRONZE
PLATING :15μ*GOLD ON MATING AREA,
GOLD FLASH PLATING ON
SOLDER TAILS, 50μ*NICKEL
UNDERPLATING OVERALL.
- 3.MECHANICAL REQUIREMENT:
3.1 DURABILITY:100 CYCLES NIN.
3.2 INSERTION AND EXTRACTION FORCE:40N MAX.& 11.5N MAX
- 4.ENVIRONMENTAL:
4.1 CONTACT RESISTANCE:20 MILLIOHMS MAXINITIAL.
4.2 DIELECTRIC WITHSTANDING VOLTAGE: 300V AC/MIN
4.3 CURRENT RATING:0.5 Amps Max.
4.4 OPERATION:-40°C TO +95C
4.5 STORAGE:-55°C TO +105°C
4.6 REFLOW SOLDERING TEMPERATURE:255~265*MAXLIMUMFOR
5~10 SECONDS
4.9 ROHS COMPLIANT
- 5.PACKAGING:TAPE AND REEL

TOLERANCE		 深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
.X±0.30	X.*±5°	PART NO.	TITLE:
.XX±0.25	X.X*±1°	SFP-15U-20P	SFP+ 1X1CONNECTOR
.XXX±0.15		DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olvia	
MATERILA	---	APPD: Ava	
FINISH	---		
			 SCALE N:A SHEET 1/3



REV.	ECN NO.	DESCRIPTION	DATE	DESIGN

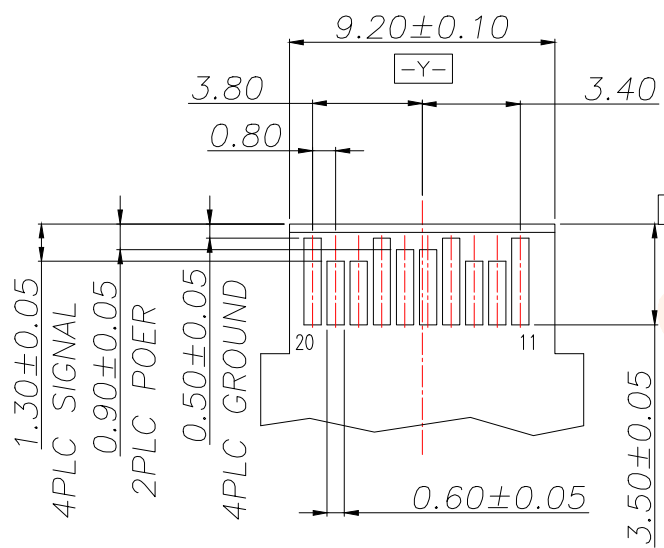


PCB.WELDING DRAWING (TOLERANCE:±0.05)

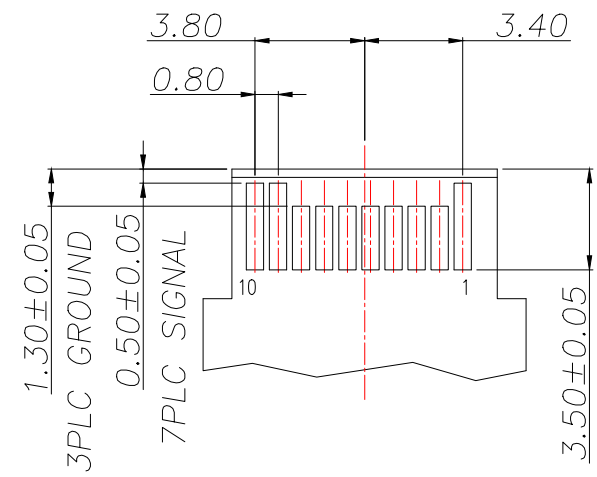
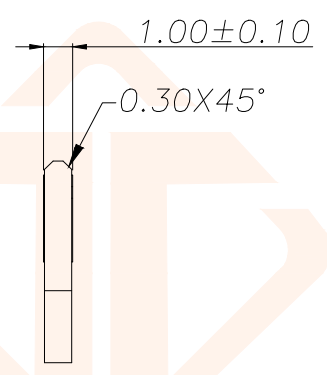
TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
.X±0.30	X.*±5°	PART NO.	TITLE:
.XX±0.25	X.X*±1°	SFP-15U-20P	SFP+ 1X1CONNECTOR
.XXX±0.15		DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olvia	
MATERILA	---	APPD: Ava	SCALE N:A SHEET 2/3



REV.	ECN NO.	DESCRIPTION	DATE	DESIGN



$\oplus 0.10 | X | Y$
 20PLC
 TOP VIEW OF BOARD



BOTTOM VIEW OF BOARD

RECOMMENDED LAYOUT DETAIL MATING TRANSCEIVER PCB

TOLERANCE		深圳聚兴泰电子科技有限公司 Shenzhen Juxingtai Electronic Technology Co., Ltd	
.X±0.30	X.*±5°	PART NO.	TITLE:
.XX±0.25	X.X*±1°	SFP-15U-20P	SFP+ 1X1CONNECTOR
.XXX±0.15		DESIGN: Ethan	MANUFACTURE DWG
UNITS	mm	CHED: Olvia	
MATERILA	---	APPD: Ava	SCALE SHEET N:A 3/3